

PROTECTION PRODUCTS

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{pk}	300	Watts
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C)

SMDA05C-8						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	6			V
Reverse Leakage Current	I_R	$V_{RWM} = 5V, T=25^\circ C$			20	μA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			9.8	V
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			17	A
Junction Capacitance	C_J	Between I/O Pins and Ground $V_R = 0V, f = 1MHz$			350	pF

SMDA12C-8						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				12	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	13.3			V
Reverse Leakage Current	I_R	$V_{RWM} = 12V, T=25^\circ C$			1	μA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			19	V
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			12	A
Junction Capacitance	C_J	Between I/O Pins and Ground $V_R = 0V, f = 1MHz$			120	pF

PROTECTION PRODUCTS
Electrical Characteristics (Continued)

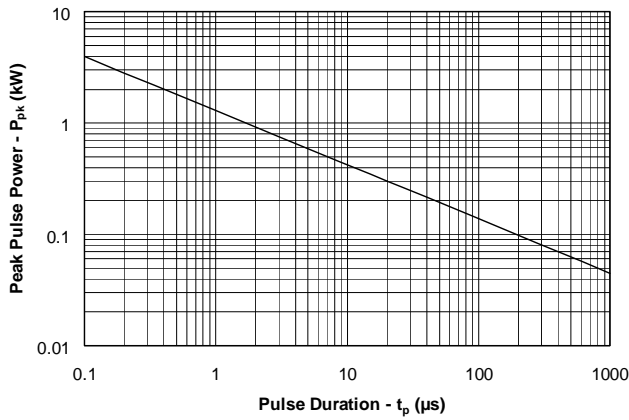
SMDA15C-8						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				15	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	16.7			V
Reverse Leakage Current	I_R	$V_{RWM} = 15V, T=25^{\circ}C$			1	μA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			24	V
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			10	A
Junction Capacitance	C_j	Between I/O Pins and Ground $V_R = 0V, f = 1MHz$			75	pF

SMDA24C-8						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				24	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	26.7			V
Reverse Leakage Current	I_R	$V_{RWM} = 24V, T=25^{\circ}C$			1	μA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			43	V
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			5	A
Junction Capacitance	C_j	Between I/O Pins and Ground $V_R = 0V, f = 1MHz$			50	pF

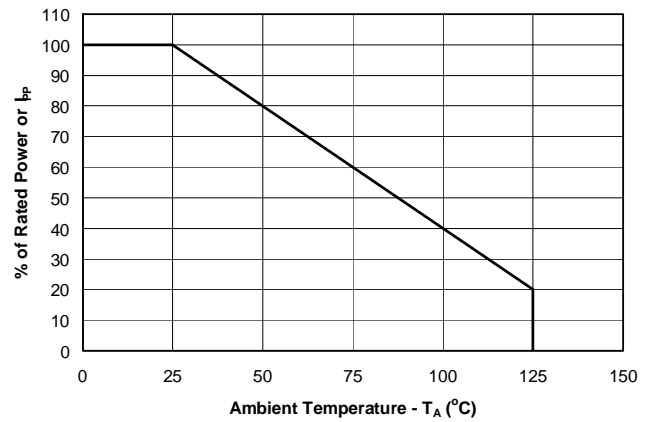
PROTECTION PRODUCTS

Typical Characteristics

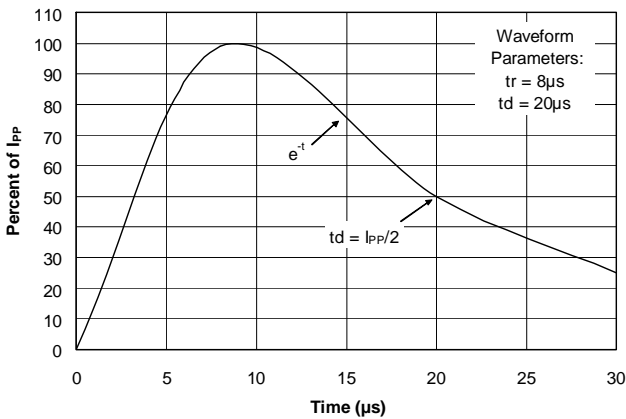
Non-Repetitive Peak Pulse Power vs. Pulse Time



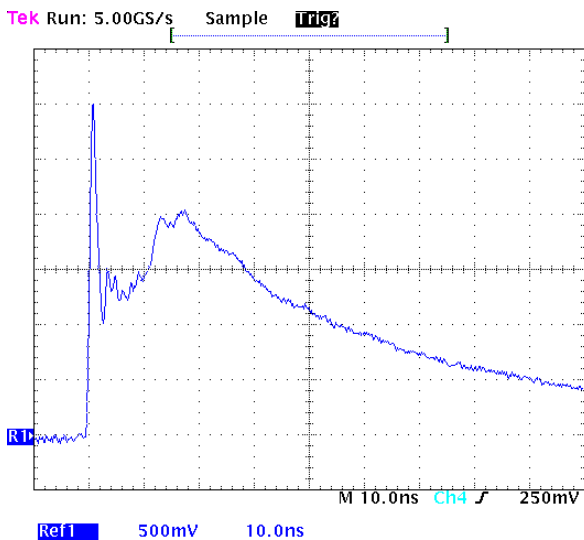
Power Derating Curve



Pulse Waveform



ESD Pulse Waveform (IEC 61000-4-2)



IEC 61000-4-2 Discharge Parameters

Level	First Peak Current (A)	Peak Current at 30 ns (A)	Peak Current at 60 ns (A)	Test Voltage (Contact Discharge) (kV)	Test Voltage (Air Discharge) (kV)
1	7.5	4	8	2	2
2	15	8	4	4	4
3	22.5	12	6	6	8
4	30	16	8	8	15

PROTECTION PRODUCTS

Applications Information

Device Connection for Protection of Eight Data Lines

The SMDAxxC-8 is designed to protect up to 8 data or I/O lines. They are bidirectional devices and may be used on lines where the signal polarities are above and below ground.

The SMDAxxC-8 TVS arrays employ a monolithic structure. Therefore, the working voltage (V_{RWM}) and breakdown voltage (V_{BR}) specifications apply to the differential voltage between any two data line pins. For example, the SMDA24C-8 is designed for a maximum voltage excursion of $\pm 12V$ between any two data lines.

The device is connected as follows:

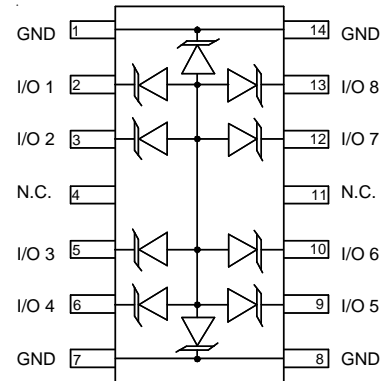
- Pins 2, 3, 5, 6, 9, 10, 12 and 13 are connected to the lines that are to be protected. Pins 1, 7, 8, and 14 are connected to ground. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces. Pins 4 and 11 are not connected.

Circuit Board Layout Recommendations for Suppression of ESD.

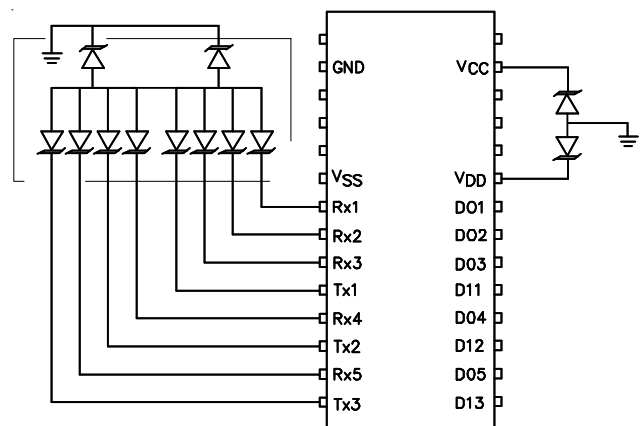
Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

Circuit Diagram



Connection Diagram

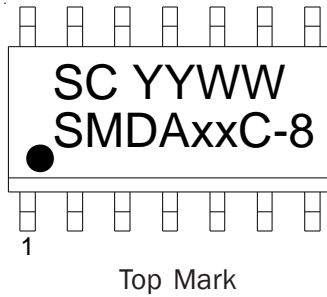


Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

PROTECTION PRODUCTS

Marking

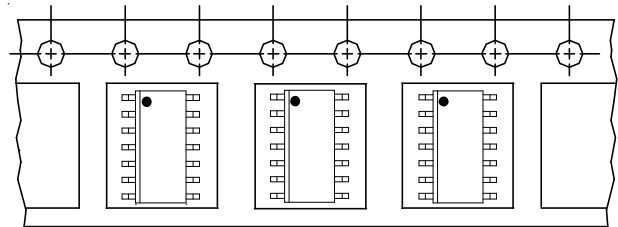
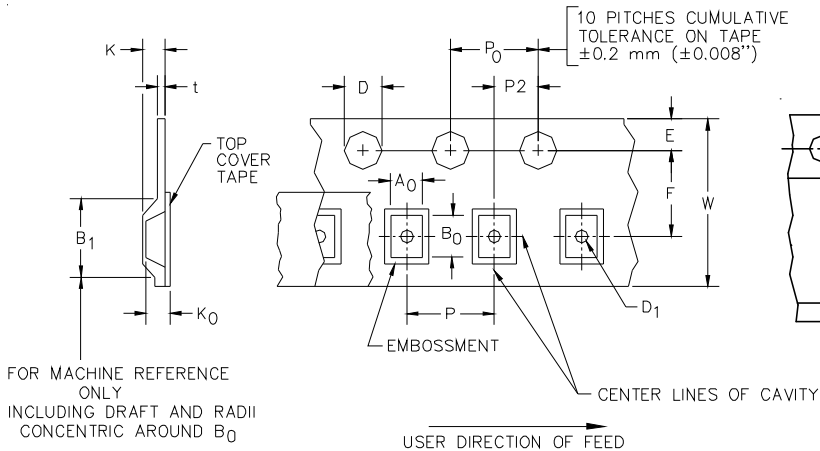


YYWW = Date Code

Ordering Information

Part Number	Lead Finish	Qty per Reel	Reel Size
SMDA05C-8.TBT	Pb Free	500	7 inch
SMDA12C-8.TBT	Pb Free	500	7 inch
SMDA15C-8.TBT	Pb Free	500	7 inch
SMDA24C-8.TBT	Pb Free	500	7 inch
SMDA05C-8.T	Pb Free	56/Tube	N/A
SMDA12C-8.T	Pb Free	56/Tube	N/A
SMDA15C-8.T	Pb Free	56/Tube	N/A
SMDA24C-8.T	Pb Free	56/Tube	N/A

Tape and Reel Specification



Device Orientation in Tape

A0	B0	K0
6.50 +/-0.30 mm	9.50 +/-0.30 mm	2.10 +/-0.15 mm

Tape Width	B, (Max)	D	D1	E	F	K (MAX)	P	P0	P2	T(MAX)	W
16 mm	12.1 mm	1.5 + 0.1 mm - 0.0 mm)	0.5 mm ±0.05	1.750±.10 mm	7.5±0.10 mm	6.5 mm	8.0±0.1 mm	4.0±0.1 mm	2.0±0.01 mm	0.4 mm	16.0 mm ± 0.3 mm

Contact Information

Semtech Corporation
Protection Products Division
200 Flynn Road, Camarillo, CA 93012
Phone: (805)498-2111 FAX (805)498-3804

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Semtech:](#)

[SMDA05C-8.TBT](#) [SMDA24C-8.TBT](#) [SMDA12C-8.TBT](#) [SMDA15C-8.TBT](#)